

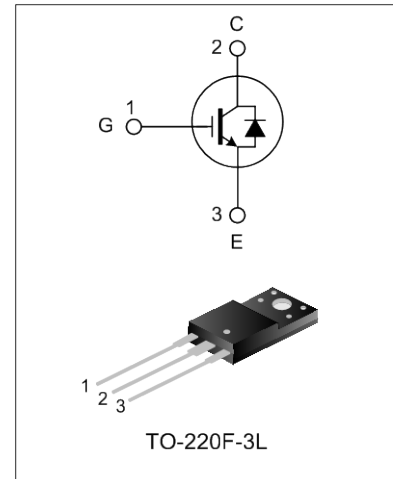
## 20A, 600V IGBT

### DESCRIPTION

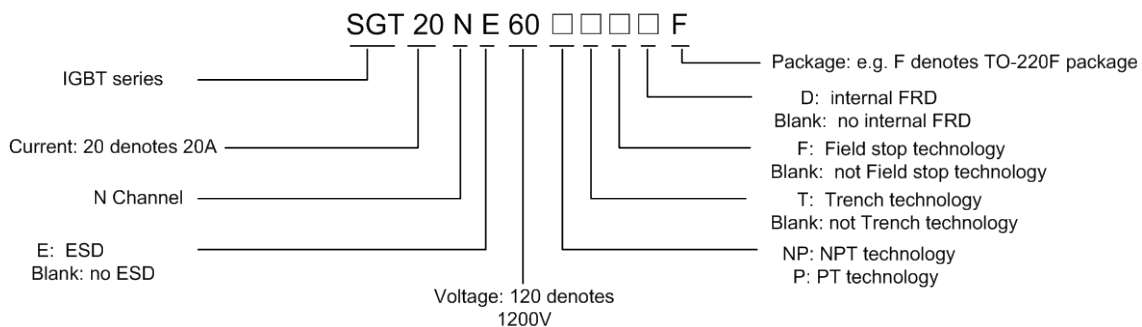
SGT20N60NPFDF using Punch Through IGBT technology, offer the optimum performance for induction Heating, UPS, SMPS and PFC application.

### FEATURES

- ◆ 20A, 600V,  $V_{CE(sat)(typ.)}=1.8V@I_C=20A$
- ◆ Low conduction loss
- ◆ Fast switching
- ◆ High input impedance
- ◆ Low Cres/Cies



### NOMENCLATURE



### ORDERING INFORMATION

Part No.	Package	Marking	Material	Packing
SGT20N60NPFDF	TO-220F-3L	20N60NPFDF	Halogen free	Tube

### ABSOLUTE MAXIMUM RATINGS (TC = 25°, UNLESS OTHERWISE NOTED)

Characteristics	Symbol	Ratings	Units
Collector to Emitter Voltage	$V_{CE}$	600	V
Gate to Emitter Voltage	$V_{GE}$	±20	V
Collector Current	$I_C$	$T_C=25^{\circ}C$	40
		$T_C=100^{\circ}C$	20
Pulsed Collector Current	$I_{CM}$	80	A
Maximum Power Dissipation ( $T_C=25^{\circ}C$ ) -Derate above 25°C	$P_D$	32	W
		0.23	W/°C
Operating Junction Temperature Range	$T_J$	-55~+150	°C
Storage Temperature Range	$T_{stg}$	-55~+150	°C

## THERMAL CHARACTERISTICS

Characteristics	Symbol	Ratings	Units
Thermal Resistance, Junction to Case (IGBT)	$R_{\theta JC}$	2.9	$^{\circ}C/W$
Thermal Resistance, Junction to Case (FRD)	$R_{\theta JC}$	5.5	$^{\circ}C/W$
Thermal Resistance, Junction to Ambient	$R_{\theta JA}$	42.5	$^{\circ}C/W$

## ELECTRICAL CHARACTERISTICS OF IGBT ( $T_C = 25^{\circ}C$ unless otherwise noted)

Characteristics	Symbol	Test conditions	Min.	Typ.	Max.	Units
Collector to Emitter Breakdown Voltage	$BV_{CE}$	$V_{GE}=0V, I_C=1mA$	600	--	--	V
C-E Leakage Current	$I_{CES}$	$V_{CE}=600V, V_{GE}=0V$	--	--	200	$\mu A$
G-E Leakage Current	$I_{GES}$	$V_{GE}=20V, V_{CE}=0V$	--	--	$\pm 400$	nA
GateThreshold Voltage	$V_{GE(th)}$	$I_C=250\mu A, V_{CE}=V_{GE}$	4.0	5.5.	7.0	V
Collector to Emitter Saturation Voltage	$V_{CE(sat)}$	$I_C=20A, V_{GE}=15V$	--	1.8	2.5	V
		$I_C=20A, V_{GE}=15V$ $T_C=125^{\circ}C$	--	2.1	--	V
Input Capacitance	$C_{ies}$	$V_{CE}=30V$	--	812	--	pF
Output Capacitance	$C_{oes}$	$V_{GE}=0V$	--	120	--	
Reverse Transfer Capacitance	$C_{res}$	$f=1MHz$	--	40	--	
Turn-On Delay Time	$T_{d(on)}$	$V_{CE}=300V$ $I_C=20A$ $R_g=24\Omega$	--	12	--	ns
Rise Time	$T_r$		--	48	--	
Turn-Off Delay Time	$T_{d(off)}$		--	109	--	
Fall Time	$T_f$		--	118	--	
Turn-On Switching Loss	$E_{on}$	$V_{GE}=15V$	--	0.61	--	mJ
Turn-Off Switching Loss	$E_{off}$	Inductive Load,	--	0.19	--	
Total Switching Loss	$E_{st}$		--	0.8	--	
Total Gate Charge	$Q_g$	$V_{CE} = 390V, I_C=5A,$ $V_{GE} = 15V$	--	46	--	nC
Gate to Emitter Charge	$Q_{ge}$		--	7	--	
Gate to Collector Charge	$Q_{gc}$		--	27	--	

## ELECTRICAL CHARACTERISTICS OF FRD ( $T_C = 25^{\circ}C$ unless otherwise noted)

Characteristics	Symbol	Test conditions	Min.	Typ.	Max.	Units
Diode Forward Voltage	$V_{FM}$	$I_F = 12A, T_C=25^{\circ}C$	--	1.9	2.6	V
		$I_F = 12A, T_C=125^{\circ}C$	--	1.5	--	
Diode Reverse Recovery Time	$T_{rr}$	$I_{ES} = 12A,$ $di_{ES}/dt=100A/\mu s$	--	32	--	ns
Diode Reverse Recovery Charge	$Q_{rr}$	$I_{ES} = 12A,$ $di_{ES}/dt=100A/\mu s$	--	31	--	nC

**TYPICAL CHARACTERISTICS CURVE**

Figure 1. Typical output characteristics

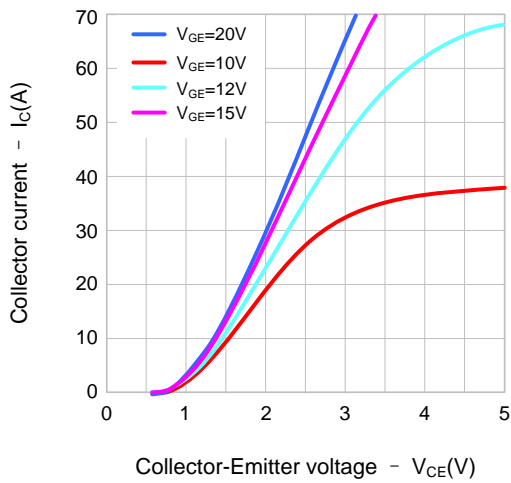


Figure 3. Transfer characteristic

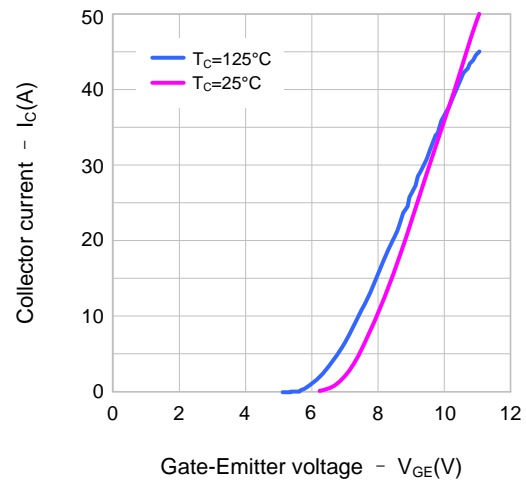


Figure 2. Typical saturation voltage characteristic

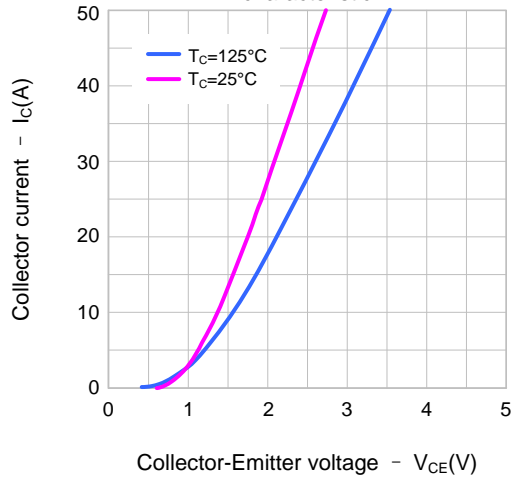


Figure 4. Saturation voltage vs.  $V_{ge}$

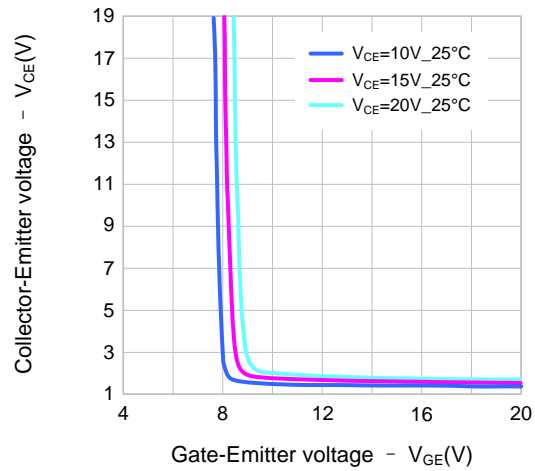


Figure 5. Saturation voltage vs.  $V_{ge}$

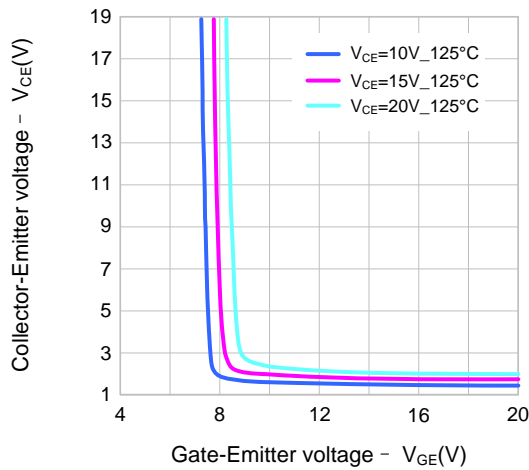
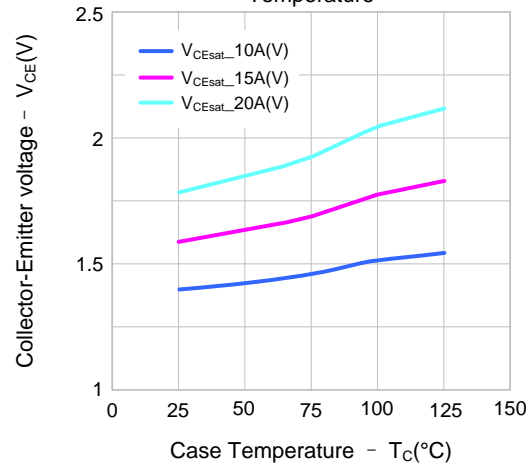


Figure 6. Saturation voltage vs. Temperature



**TYPICAL CHARACTERISTICS CURVE (CONTINUED)**

Figure 7. Capacitance characteristic

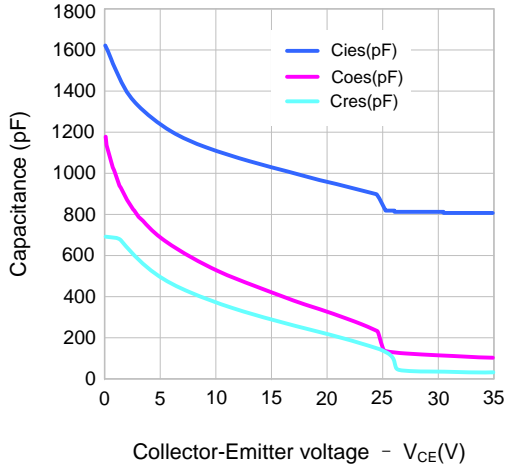


Figure 8. Gate charge characteristic

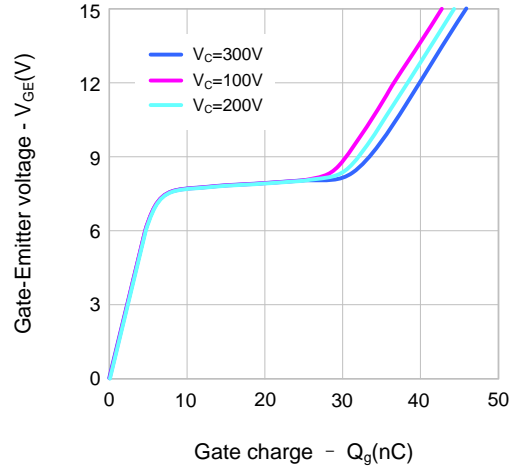


Figure 9. Turn-on characteristic vs. Gate resistance

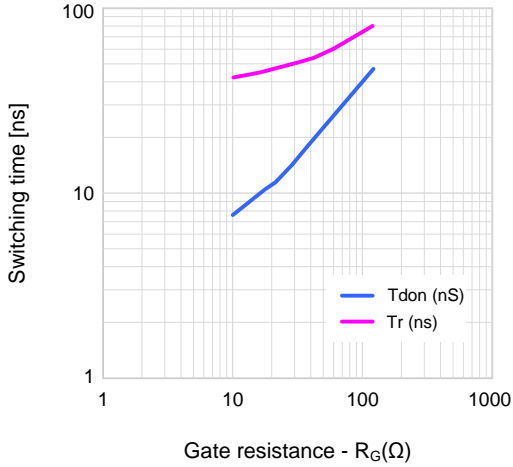


Figure 10. Turn-off characteristic vs. Gate resistance

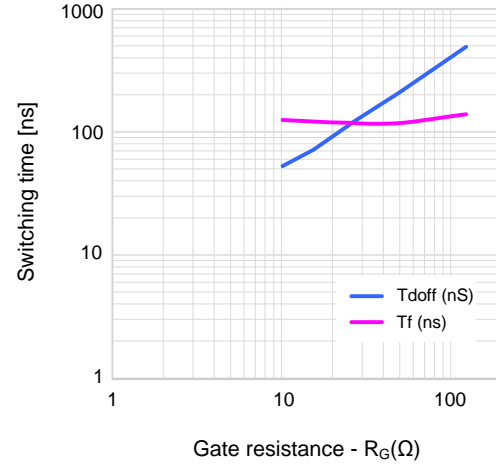


Figure 11. Switching loss vs. Gate resistance

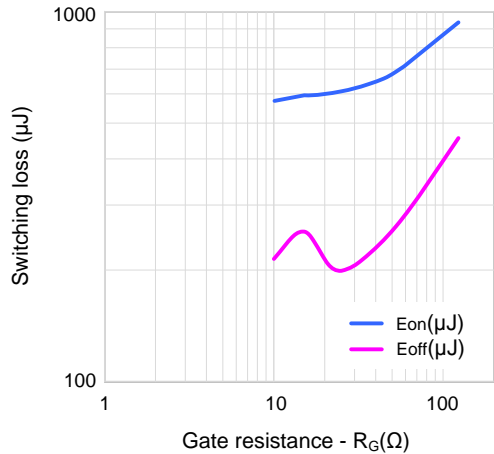
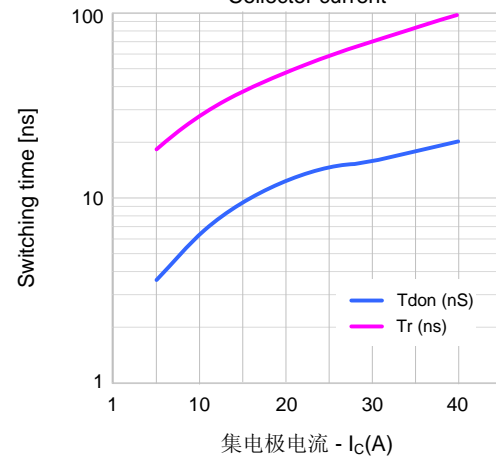


Figure 12. Turn-on characteristic vs. Collector current



**TYPICAL CHARACTERISTICS CURVE (CONTINUED)**

Figure 13. Turn-off characteristic vs. Collector current

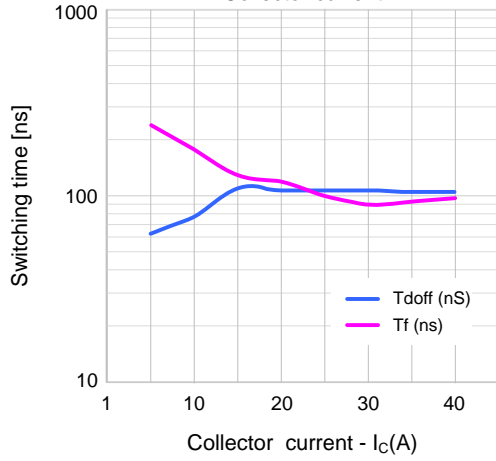


Figure 14. Switching losses vs. Collector current

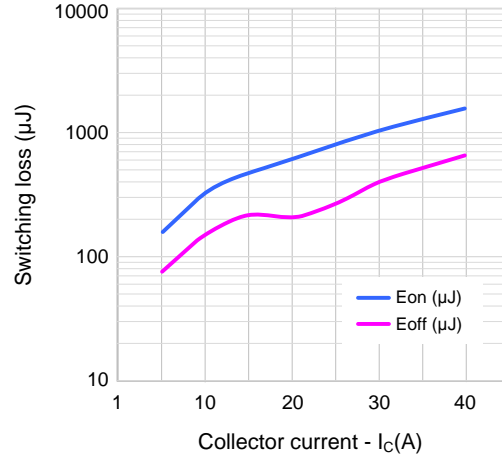


Figure 15. Forward characteristic

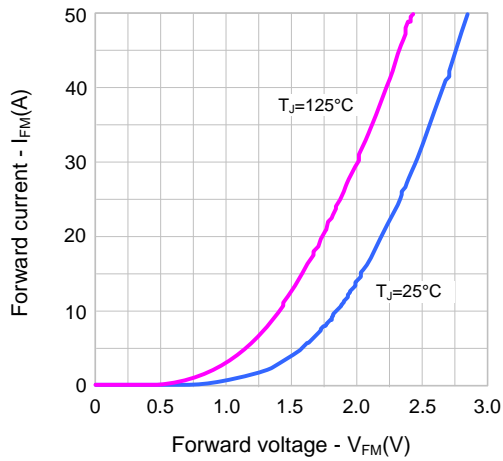
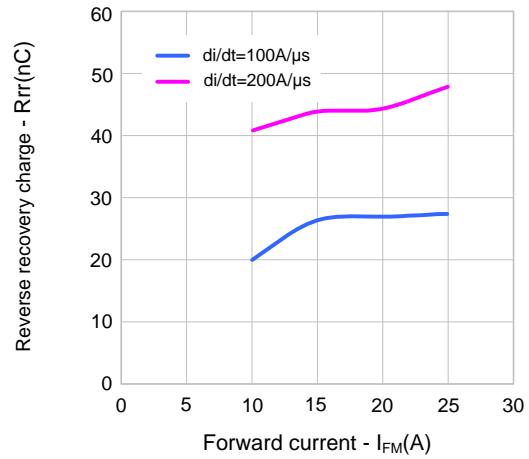
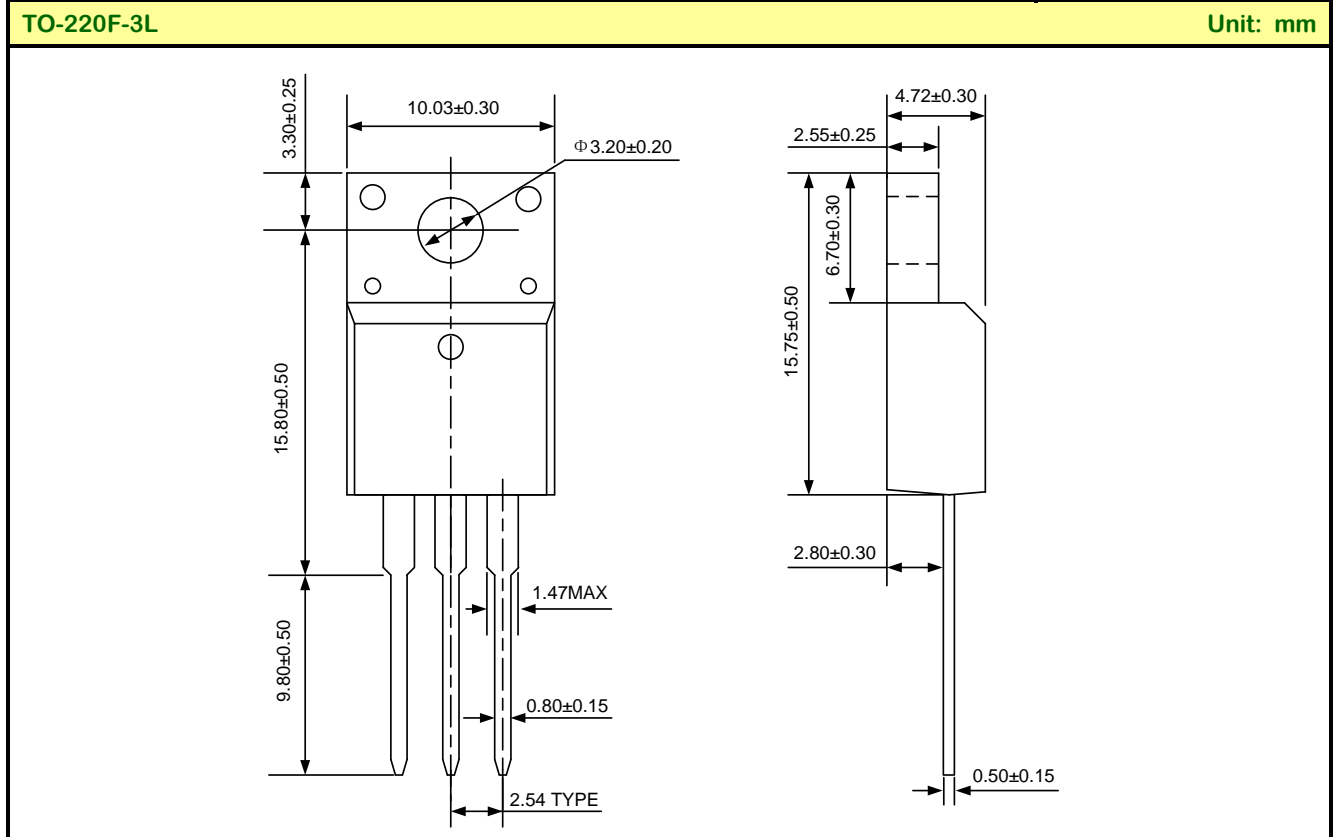


Figure 16. Reverse recovery charge vs. Forward current



**PACKAGE OUTLINE**



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Rev.:	1.2	Author:	Zhang Kefeng
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Revision History:

1. Add pin No.

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Rev.:	1.1	Author:	Zhang Kefeng
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Revision History:

1. Modify the absolute maximum ratings

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Rev.:	1.0	Author:	Zhang Kefeng
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Revision History:

1. First release
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